





Suzhou LiShengDa Electronic Technology Co., Ltd

APPROVAL SHEET NO.: NQ-APS-042

LRLN Series Metal Alloy Long Terminal Low-Resistance Resistor Product Specifications

Rev. A0

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Features

- Metal Alloy Long Terminal Low-Resistance Resistor
- Low thermal EMF
- Low TCR
- Low inductance

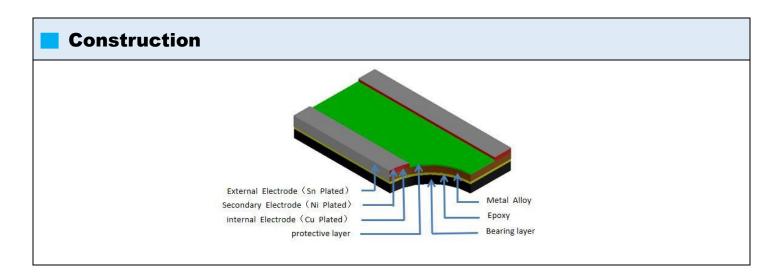
Applications

- Battery pack
- Inverter/Converter
- Consumer electronics
- Notebook

Part number

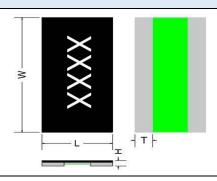
Explanation Of Part Numbers: LRLN06CFTR010A = LRLN series 0612 Size 1W 1% $5m\Omega$

LRLN	<u>06</u>	<u>C</u>	<u>F</u>	Ţ	R005	A
Series	Dimension	Rated	Tolerance	Packaging	Resistance	Terminals
		Power				
LRNN: Metal alloy	06: 0612	C: 1W	D:0.5% ;F:1%	T:Paper	R005=5mΩ	A: 2 terminal
long terminal	05: 0508		;J:5%			B: 4 terminal
Resistor						





Physical Dimensions (mm)



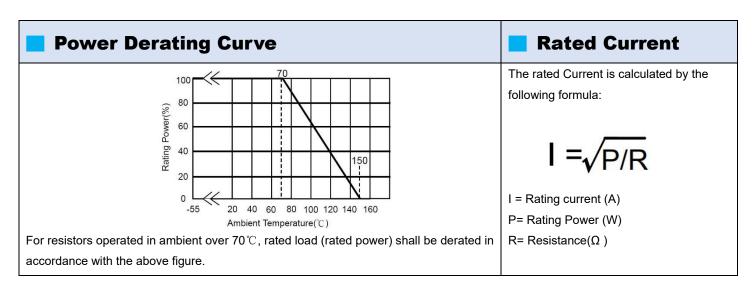
Unit: mm

Size	R Value	L	W	Н	Т
0612	1mΩ	1.60±0.20	3.20±0.20	Max 0.40	0.40±0.15
0612	1.5mΩ~25 mΩ	1.60±0.20	3.20±0.20	Max 0.35	0.40±0.15
0508	1mΩ	1.26±0.20	2.06±0.20	Max 0.40	0.35±0.15
0508	1.5mΩ~10 mΩ	1.26±0.20	2.06±0.20	Max 0.35	0.35±0.15

Standard Electrical Specifications

Size	Power Rating	Resistance	TCR	Resistance	Rating	Operation
	at 70℃(W)	Range (mΩ)	(ppm/℃)	Tolerance (%)	Current	Temperature Range
0612	1	1~2	±70			
0612	1	3~25	±50	D:0.5% ;F:1%	(P/R) ^{1/2}	-55℃~+150℃
0508	1	1~2	±100	;J:5%		
0508	1	3~10	±70			

^{*} Note: P=Rating Power; R=Resistance Value





Marking Format :

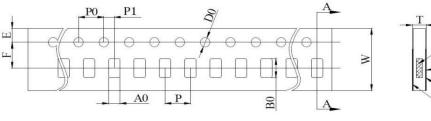
For 0612 Size is marked with four digit. We have two different ways of marking:

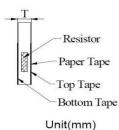
- a. "R" designates the decimal location in ohms, e.g. $1m\Omega$: R001; $10m\Omega$: R010;
- b. "m" designates the decimal location in milliohms, e.g. $0.5m\Omega$: 0m50; $5.5m\Omega$: 5m50;

For 0508 Size is marked with three digit. We have two different ways of marking:

- a. "R" designates the decimal location in ohms, e.g. $1m\Omega$: 001; $10m\Omega$: 010
- b. "m" designates the decimal location in milliohms, e.g. $0.5m\Omega$: 0m5; $1.5m\Omega$: 1m5

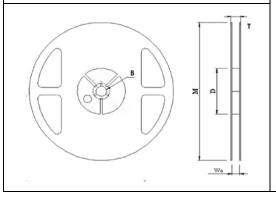
Taping specification





Size	0612	0508
A0	2.00±0.20	1.66±0.20
B0	3.60±0.20	2.46±0.20
Е	1.75±0.10	1.75±0.10
F	3.50±0.05	3.50±0.05
W	8.00±0.20	8.00±0.20
P0	4.00±0.10	4.00±0.10
Р	4.00±0.10	4.00±0.10
P1	2.00±0.05	2.00±0.05
D0	1.50±0.10	1.50±0.10
Т	0.55±0.20	0.55±0.20

▲ Reel Dimensions



Series	М	W	A	В	С	D
LRNN	178.0±2.0	8.4+0.5/-0	2.0±0.5	13.2±0.5	17.70±0.5	60.0±1.0

▲ Quantity of Package

Size	Quantity (pcs)
0612/0508	5,000

unit: mm



Reliability test item < Electrical Performance>

ltem		Test condition/ M	ethods	Limited	Standard
Temperature coefficient of resistance	TCR =(R-R ₀)/R ₀ (T2-T1)X 10 ⁶ R ₀ : resistance of room temperature R: resistance of 125 $^{\circ}$ C; T1: Room temperature T2: Temperature at 125 $^{\circ}$ C			Refer to Spec	MIL-STD- 202 Method 304
		ead for 5 seconds , the Test condition refer to belo			
Short time	Type Resistance(mΩ) Power rating		≤±1.0%	IEC60115-1	
Overload	0612	1≤R≤10	4 times	<u>=</u> ±1.070	4.13
	0612	10 < R ≤ 25	3 times		
	0508	1≤R≤10	3 times		
	0308	9≤R≤10	3 times		
Resistance to Soldering Heat	260℃±5℃ tim	e: 12sec± 0.5sec		≤±0.5%	MIL-STD- 202 Method 210
Solderability	Temperature of Solder: 245±5℃ Dipping time:3±0.5s			Solder coverage over 95%	IEC60115-1 4.17
Temperature Cycling	-55℃ (15min)/+150℃(15min), 300 cycles			≤±1.0%	MIL-STD-202
Low temperature Storage	-55℃ for 1000hours, No power			≤±1.0%	IEC60115-1 4.23.4
High Temperature Storage	150℃ for 1000hours, No power			≤±1.0%	IEC60115-1 4.25
Bias Humidity	+85℃, 85% RH, 10%bias, 1000hours			0612: 1.5~10mR, \triangle R \leq ±1% 11~20MR, \triangle R \leq ±2%% 0508: 1~8mR, \triangle R \leq ±1% 9~10MR, \triangle R \leq ±2%	MIL-STD-202
Vibration	The frequency varies from 10HZ to 55HZ and return to 10HZ, shall be transferred in 1 min. Amplitude : 1.5mm, 3 directions, and 12 hours			≤±0.5%	MIL-STD-202
Operational life	70℃± 2℃, 1000 hours, at rated power 1.5 hours "ON", 0.5 hours "OFF"			0612: $1.5 \sim 9MR, \triangle R \leq \pm 1\%$ $10 \sim 14MR, \triangle R \leq \pm 3\%$ $15 \sim 20MR, \triangle R \leq \pm 5\%$ 0508: $1 \sim 8mR, \triangle R \leq \pm 1\%$ $9 \sim 10mR, \triangle R \leq \pm 3\%$	Method 201
Moisture resistance	MIL-STD-202,n	nethod106, No power, 7l	o not required	≤±0.5%	MIL-STD-202

Note: Measurement at 24±4 hours after test conclusion for all reliability tests-parts.

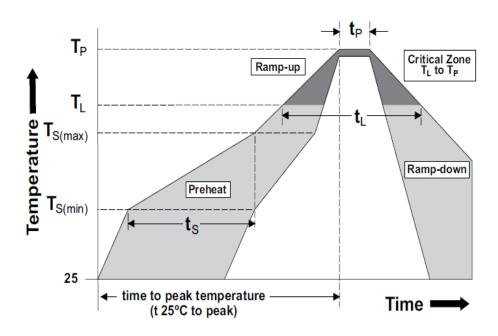


Recommend Soldering Method:

This is for recommendation, please customer perform adjustment according to actual application

*Recommend solder paste: 96.5Sn/3.0Ag/0.5Cu

♦ IR Reflow-Soldering Profile



	Reflow Condition	Pb – Free assembly	
	- Temperature Min (T₅(min))	150°C	
Pre heat	- Temperature Max (T _s (max))	200°C	
	- Time (Min to Max) (t _s)	60 – 180 secs	
Average ra	mp up rate (Liquidus Temp (T∟) to peak	5°C/second max	
T _s (m	ax) to T∟ - Ramp-up Rate	5°C/second max	
Defless	- Temperature (T _L) (Liquidus)	217°C	
Reflow	- Time (t∟)	60 – 150 seconds	
P	eak Temperature (T _P)	260°C	
Time	within 5°C of actual peak Temperature (t _p)	10 – 30 seconds	
	Ramp-down Rate	6°C/second max	
Time 25	°C to peak Temperature (T _P)	8 minutes Max.	
	Wave Soldering	260°C, 10 seconds max.	
	Hand Soldering	350°C, 5 seconds max.	

Recommended IR Reflow Soldering Profile MEET J-STD-020D

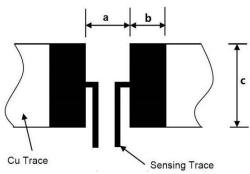
♦ Soldering Iron:

Unit: mm



Temperature 350°C±10°C, dwell time shall be less than 3 sec.

Recommended Solder Pad Layout



Size	а	b	С
0612	0.80	1.00	3.50
0508	0.50	0.90	2.30

Label



Storage requirement

*The temperature condition must be controlled at $5\sim35^{\circ}$ C, the R.H. must be controlled at $40\sim75\%$. The stock can maintain quality level in two years.

- **Please avoid the mentioned harsh environment below when storing to ensure product performance and its' weld ability. Places exposed to sea breeze or other corrosive gas, such as Cl2、H2S、NH3、SO2 and NO2.
- ***When the product is moved and stored, please ensure the correct orientation of the box. Do not drop or squeeze the box. Otherwise, the electrode or the body of the product may be damaged.

Operation and Processing Precautions:

- ①Handle with care when printing circuit board (PCB) is divided or fixed on support body, because bending of printing circuit board (PCB) mounting will make mechanical stress for resistors..
- ②Make sure the power rating is under the limit when using the resistor. When power rating is over the limit, the resister will be overloaded. There might be machinery damage due to the climbing temperature.
- ③Avoid damage to the edge of resistor and protective layer caused by mechanical stress.

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